

IN THE CLAIMS:

Claims 1-6 have been amended herein. All of the pending claims 1 through 6 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) A method for packaging a flip-chip semiconductor assembly, comprising:  
providing at least one integrated circuit (IC) die having bond pads on a surface thereof;  
providing a substrate having electrical pads for mounting ~~said the~~ at least one IC die thereto;  
placing dry conductive epoxy dots on ~~said the~~ electrical pads on ~~said the~~ substrate;  
attaching ~~said the~~ at least one IC die to ~~said the~~ substrate with ~~said the~~ bond pads of ~~said the~~ at least one IC die in contact with ~~said the~~ dry conductive epoxy dots on ~~said the~~ electrical pads on ~~said the~~ substrate to form ~~said the~~ flip-chip semiconductor assembly;  
testing ~~said the~~ flip-chip semiconductor assembly;  
if ~~said the~~ flip-chip semiconductor assembly fails ~~said~~ testing, then reworking ~~said the~~ flip-chip semiconductor assembly and retesting ~~said the~~ flip-chip semiconductor assembly or scrapping ~~said the~~ flip-chip semiconductor assembly if ~~said the~~ flip-chip semiconductor assembly has already been reworked a preset number of times; and  
if ~~said the~~ flip-chip semiconductor assembly passes ~~said~~ testing, then encapsulating ~~said the~~ at least one IC die on ~~said the~~ substrate.

2. (Currently Amended) The method of claim 1, wherein ~~said~~ providing ~~said the~~ substrate comprises providing a printed circuit board (PCB).

3. (Currently Amended) The method of claim 1, wherein ~~said~~ placing ~~said the~~ dry conductive epoxy dots comprises placing thermoplastic epoxy and further comprising heating ~~said the~~ thermoplastic epoxy followed by cooling ~~said the~~ flip-chip semiconductor assembly.

4. (Currently Amended) The method of claim 1, wherein ~~said~~ attaching ~~said~~ the at least one IC die to ~~said~~ the substrate comprises:  
aligning ~~said~~ the bond pads on ~~said~~ the at least one IC die with ~~said~~ the dry conductive epoxy dots on ~~said~~ the electrical pads on ~~said~~ the substrate;  
contacting ~~said~~ the aligned bond pads on ~~said~~ the at least one IC die with ~~said~~ the dry conductive epoxy dots on ~~said~~ the substrate; and  
heating ~~said~~ the flip-chip semiconductor assembly to form electrical connections between ~~said~~ the bond pads on ~~said~~ the at least one IC die and ~~said~~ the electrical pads on ~~said~~ the substrate.

5. (Currently Amended) The method of claim 1, further comprising speed grading ~~said~~ the at least one IC die.

6. (Currently Amended) The method of claim 5, wherein ~~said~~ speed grading is performed after testing ~~said~~ the flip-chip semiconductor assembly.